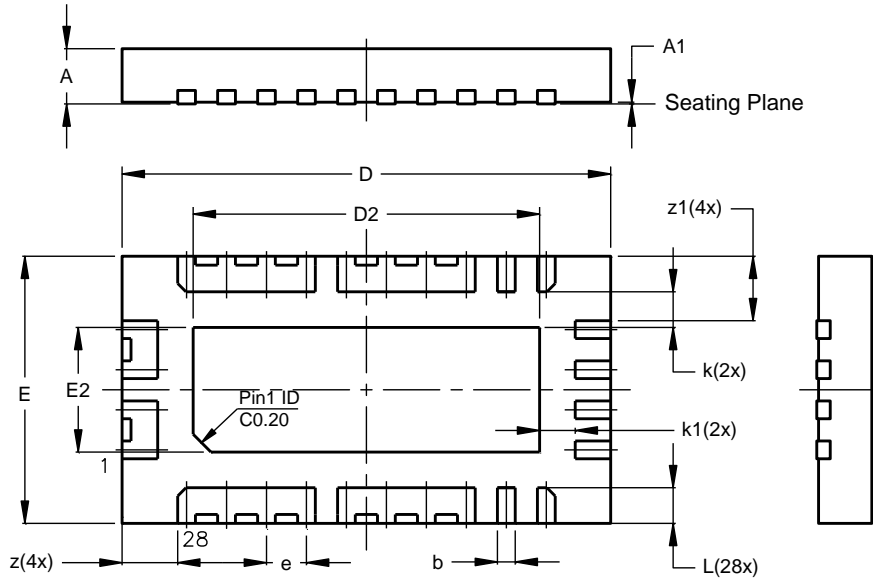


Package Outline Dimensions

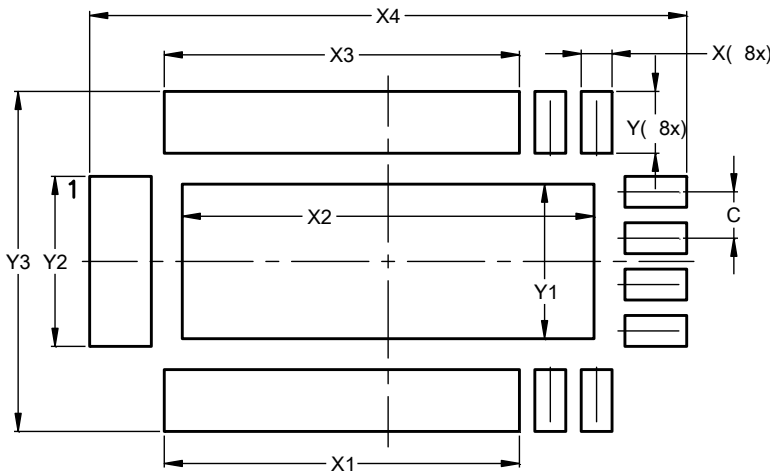
U-QFN3055-28



U-QFN3055-28			
Dim	Min	Max	Typ
A	0.55	0.65	0.60
A1	0.00	0.05	0.02
b	0.15	0.25	0.20
D	5.45	5.55	5.50
D2	3.85	3.95	3.90
E	2.95	3.05	3.00
E2	1.35	1.45	1.40
e	0.45 BSC		
k	--	--	0.40
k1	--	--	0.40
L	0.35	0.45	0.40
z	--	--	0.625
z1	--	--	0.725
All Dimensions in mm			

Suggested Pad Layout

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Dimensions	Value (in mm)
C	0.450
X	0.300
X1	3.450
X2	4.000
X3	3.450
X4	5.800
Y	0.600
Y1	1.500
Y2	1.650
Y3	3.300

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.